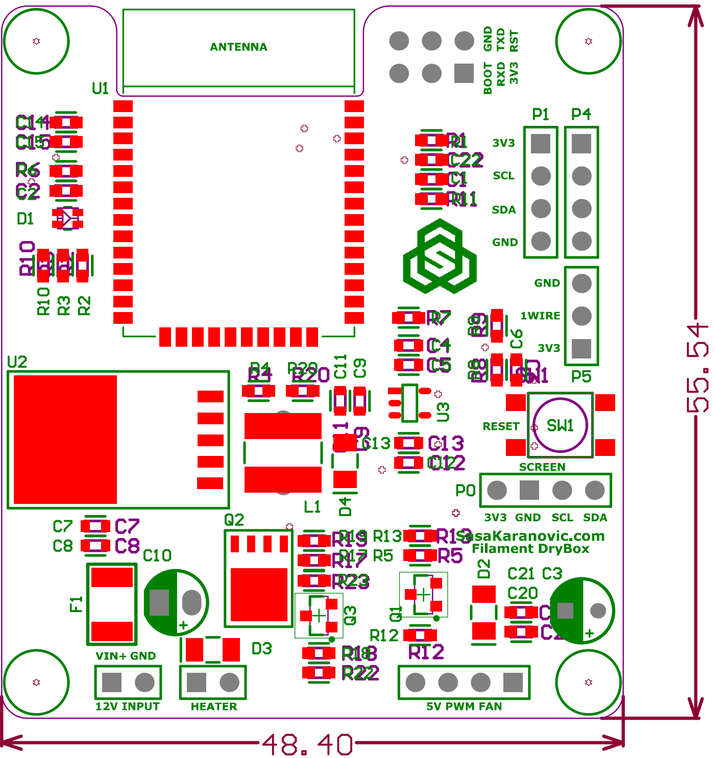
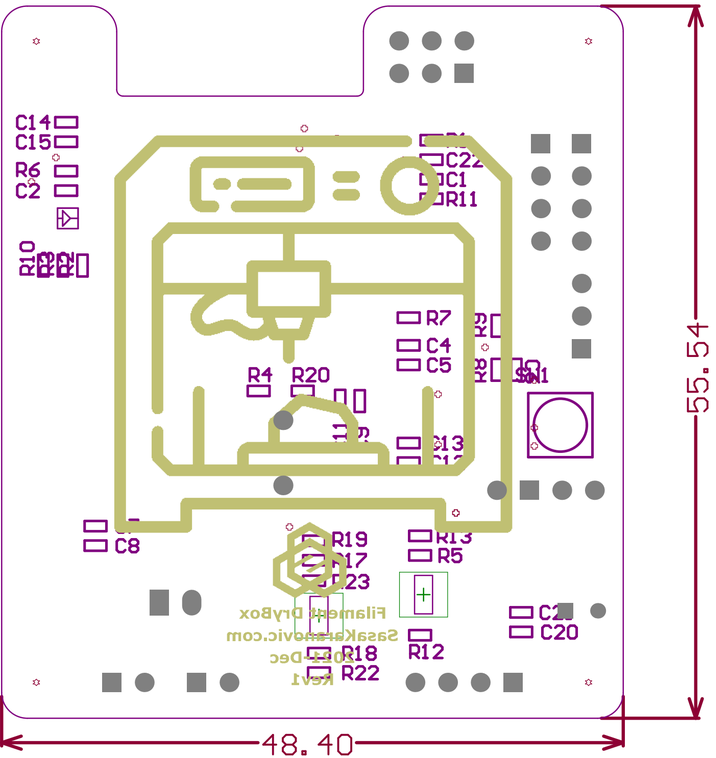


Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.010mm	3.5	
1	Top Layer		0.036mm		
	Dielectric 1	FR-4	0.320mm	4.8	
2	Bottom Layer		0.036mm		
	Bottom Solder	Solder Resist	0.010mm	3.5	
	Bottom Overlay				

Symbol	Count	Hole Size	Plated	Hole Type	Via/Pad	Pad Shape
✠	16	0.400mm (15.75mil)	PTH	Round	Via	Rounded
○	2	0.762mm (30.00mil)	PTH	Round	Pad	Rounded
▽	4	0.800mm (31.50mil)	PTH	Round	Pad	(Mixed)
□	29	0.900mm (35.43mil)	PTH	Round	Pad	(Mixed)
✡	4	3.000mm (118.11mil)	NPTH	Round	Pad	Rounded
	55 Total					



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